

Title (en)

APPARATUS AND METHOD FOR ELECTROPLATING A WAFER SURFACE

Title (de)

VORRICHTUNG UND VERFAHREN ZUR ELEKTROPLATTIERUNG EINER WAFEROBERFLÄCHE

Title (fr)

APPAREIL ET PROCEDE DE GALVANOPLASTIE D'UNE SURFACE DE PLAQUETTE

Publication

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Application

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Abstract (en)

[origin: WO03056609A2] The present invention provides for a method of electroplating a wafer surface comprising introducing a plating liquid to the wafer surface in a chamber and rotating the wafer about an axis of rotation passing through the surface to be plated, and including the further step of moving the wafer such that its axis of rotation is itself caused to rotate about a second axis of rotation.

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